Abstracts

2W Ku-band coplanar MMIC HPA using HBT for flip-chip assembly

J.P. Fraysse, O. Vendier, M. Soulard and P. Auxemery. "2W Ku-band coplanar MMIC HPA using HBT for flip-chip assembly." 2002 MTT-S International Microwave Symposium Digest 02.1 (2002 Vol. I [MWSYM]): 441-444 vol.1.

A coplanar HBT MMIC amplifier in Ku-band for space applications is presented. This HPA is based on the commercial HB20P process of UMS adapted to flip-chip assembly. An output power closed to 2W has been measured over 10.5-12.2GHz frequency range with an associated PAE higher than 25% and an associated gain of 20dB. The coplanar technology (CPW) and flip-chip mounting impact on the HPA design is also described.

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